

**TRANSMITTAL OF FORMAL DRAWINGS**Docket No.
POU920000117US1

In Re Application Of: CHEN et al.

J

Serial No.	Filing Date	Batch No.	Examiner	Art Unit
09/740,411	12/19/00			2131

Invention: CIRCUITS AND METHODS FOR MODULAR EXPONENTIATION

Address to:

**Assistant Commissioner for Patents
Washington, D.C. 20231**

Transmitted herewith are:

29 sheets of formal drawing(s) for this application.

Each sheet of drawing indicates the identifying indicia suggested in 37 CFR Section 1.84(c) on the reverse side of the drawing.

Lawrence D. Cutter
Signature**LAWRENCE D. CUTTER, Sr. Attorney**
Reg. No. 28,501
IBM Corporation
2455 South Rd., M/S P386
Poughkeepsie, NY 12601
(845) 433-1172Dated: June 26, 2001

I certify that this document and attached formal drawings are being deposited on 6-26-01 with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.

Signature of Person Mailing Correspondence**Susan L. Phelps**

Typed or Printed Name of Person Mailing Correspondence

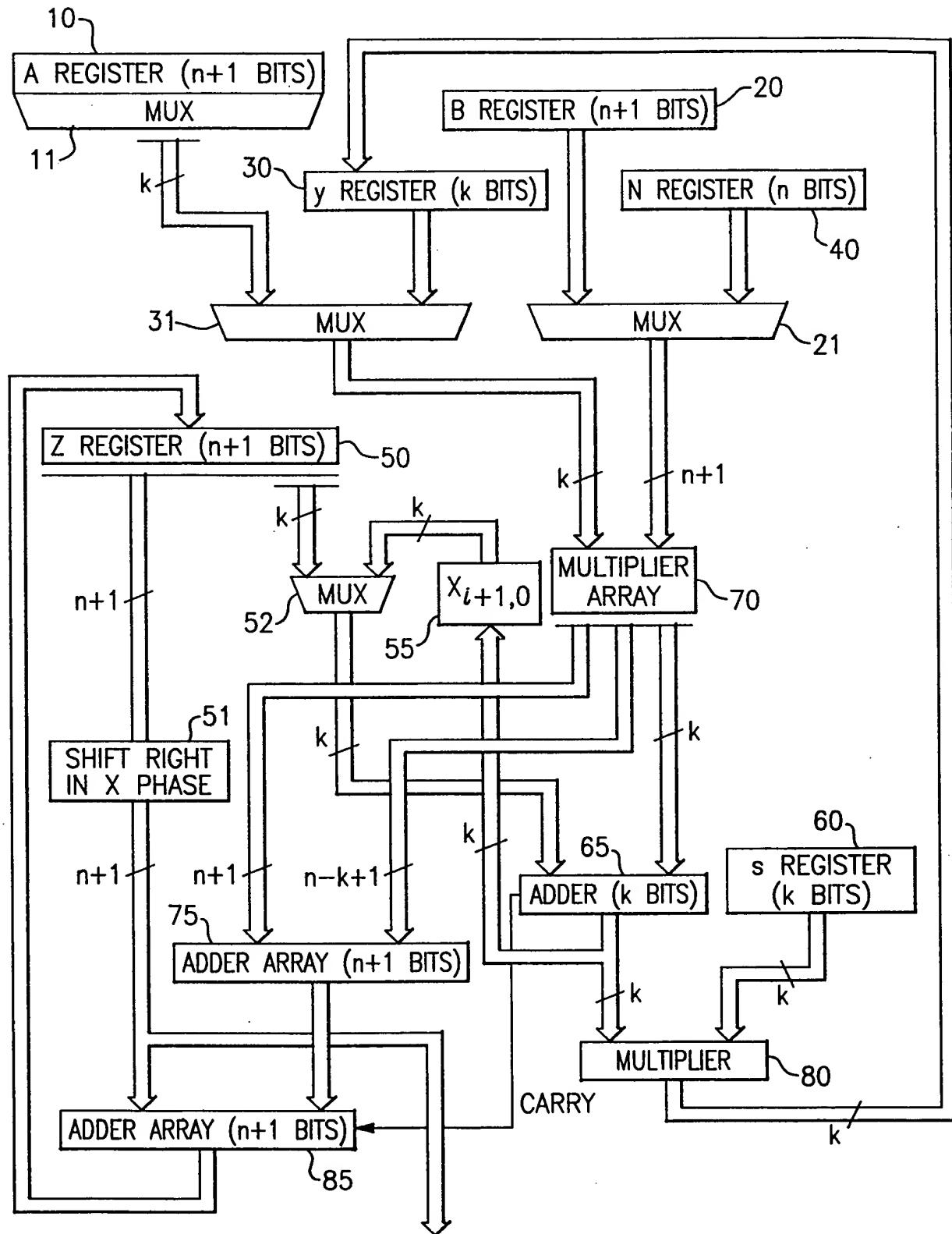
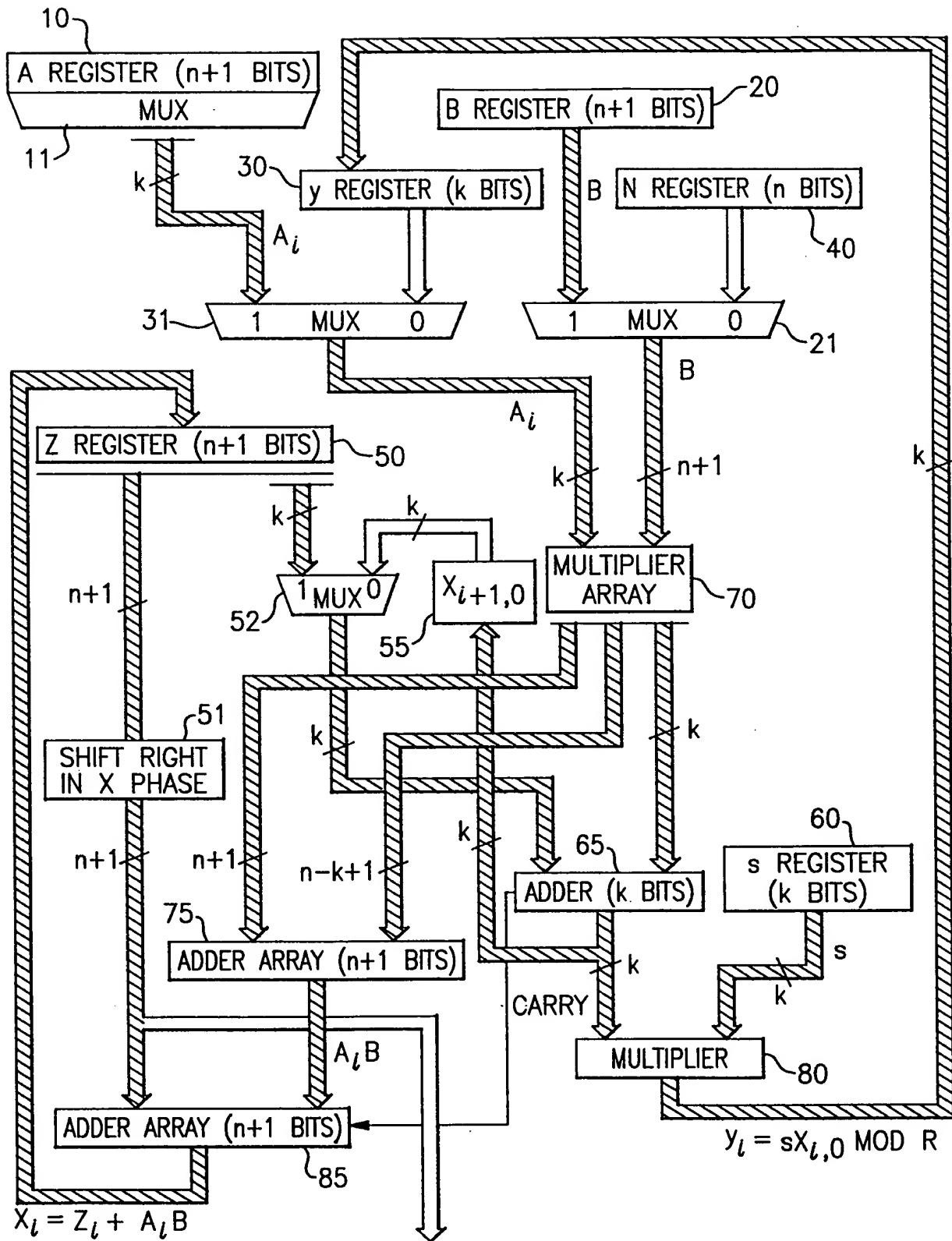


FIG.1

**FIG.2**

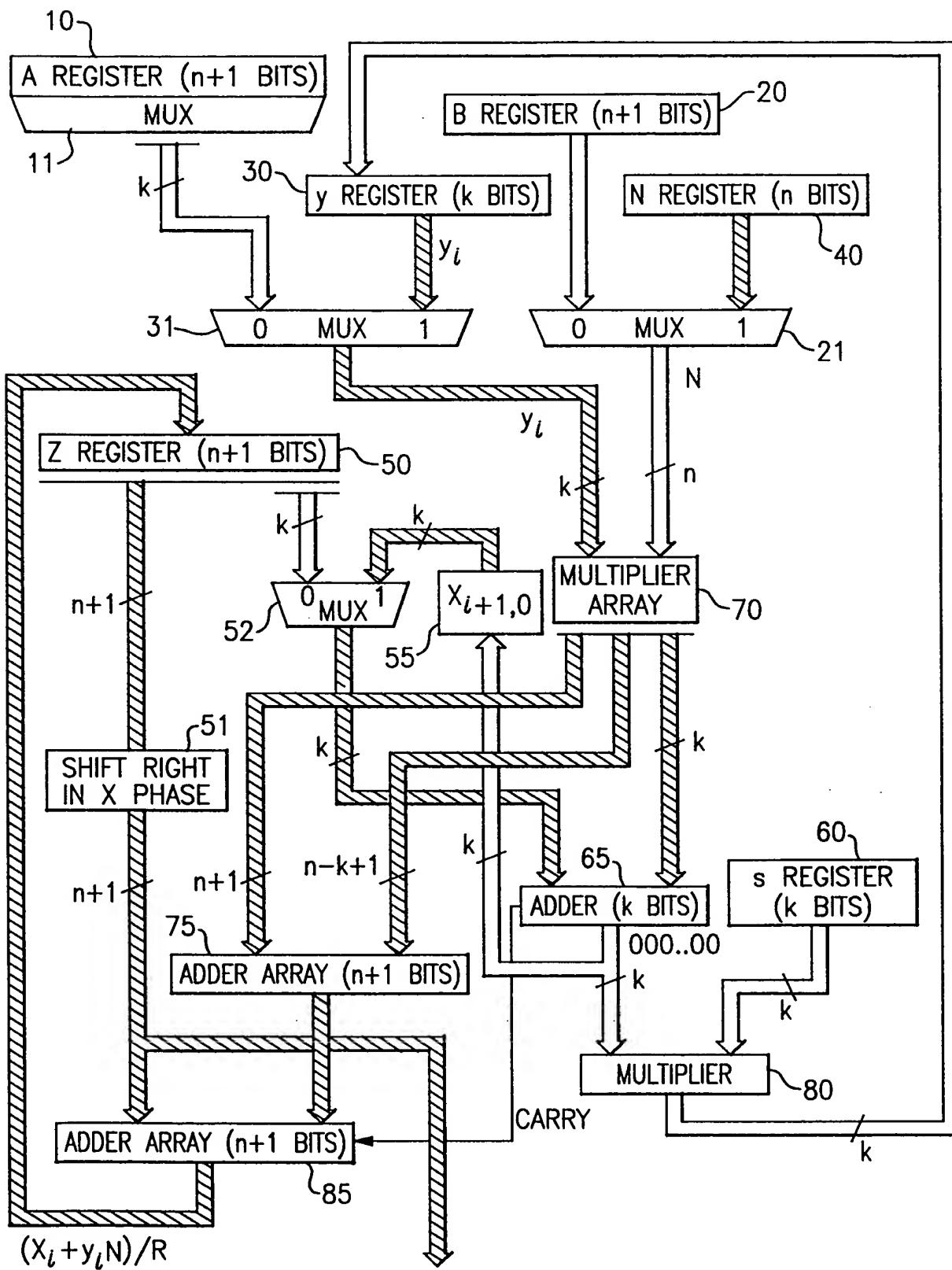


FIG.3

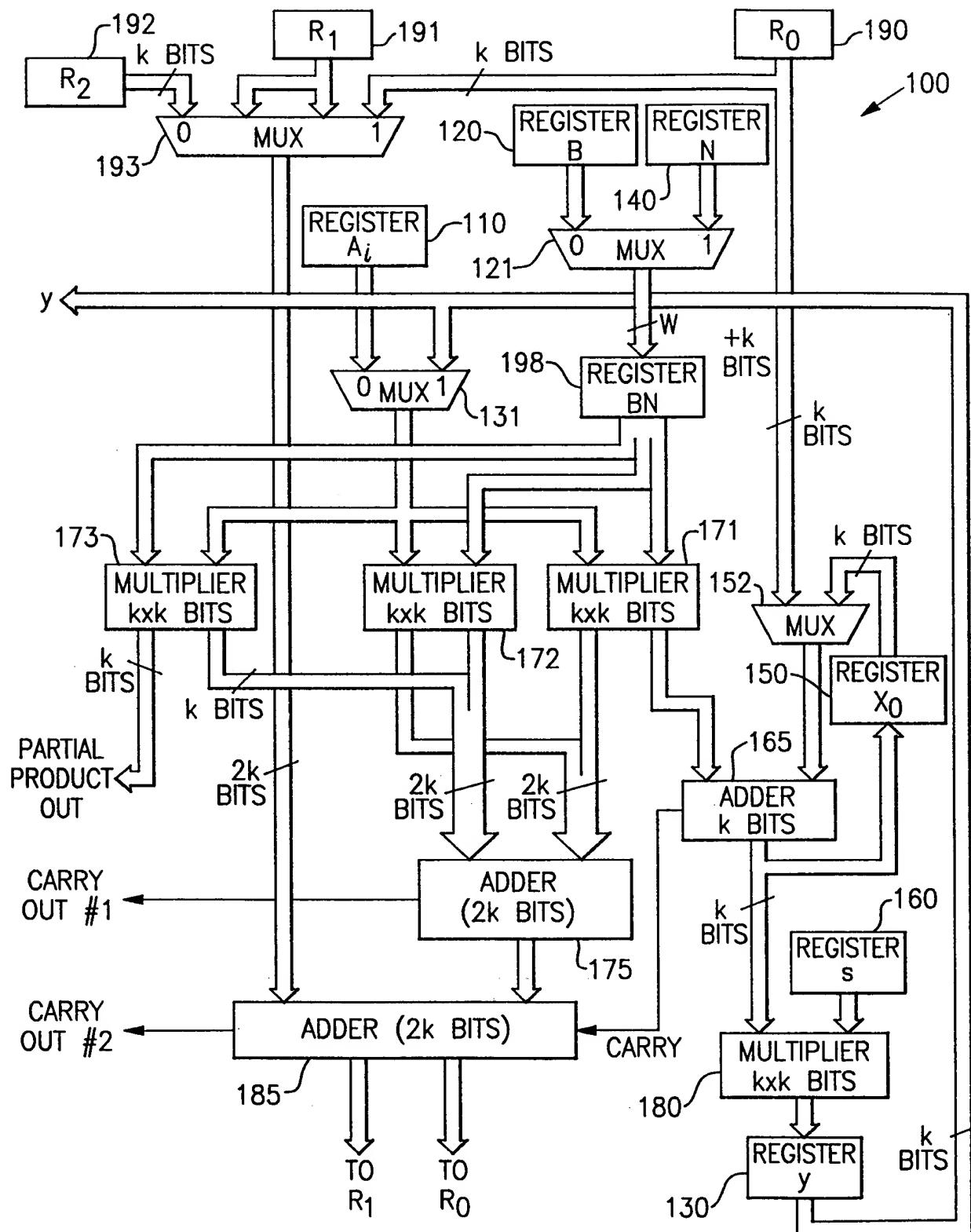


FIG.4

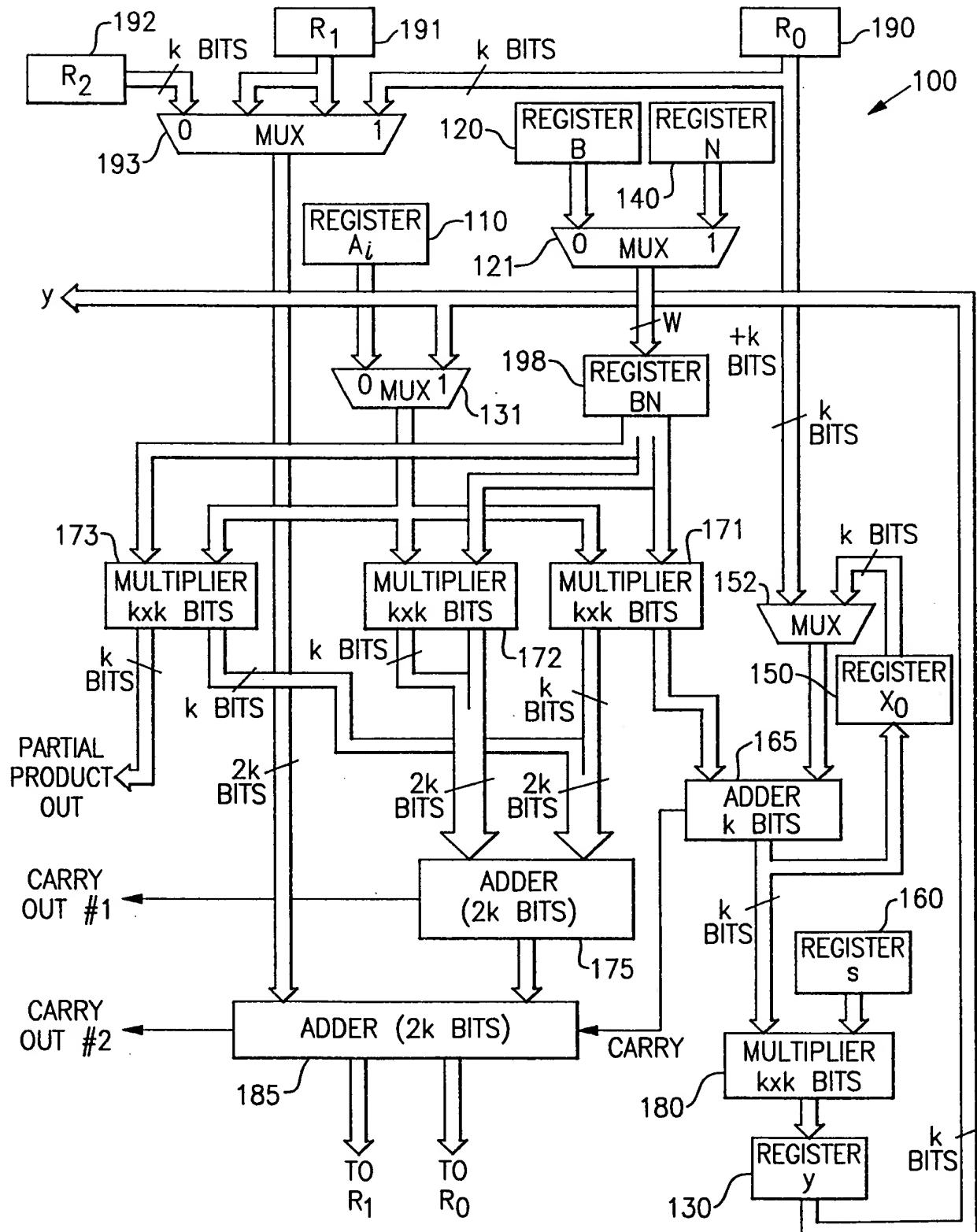
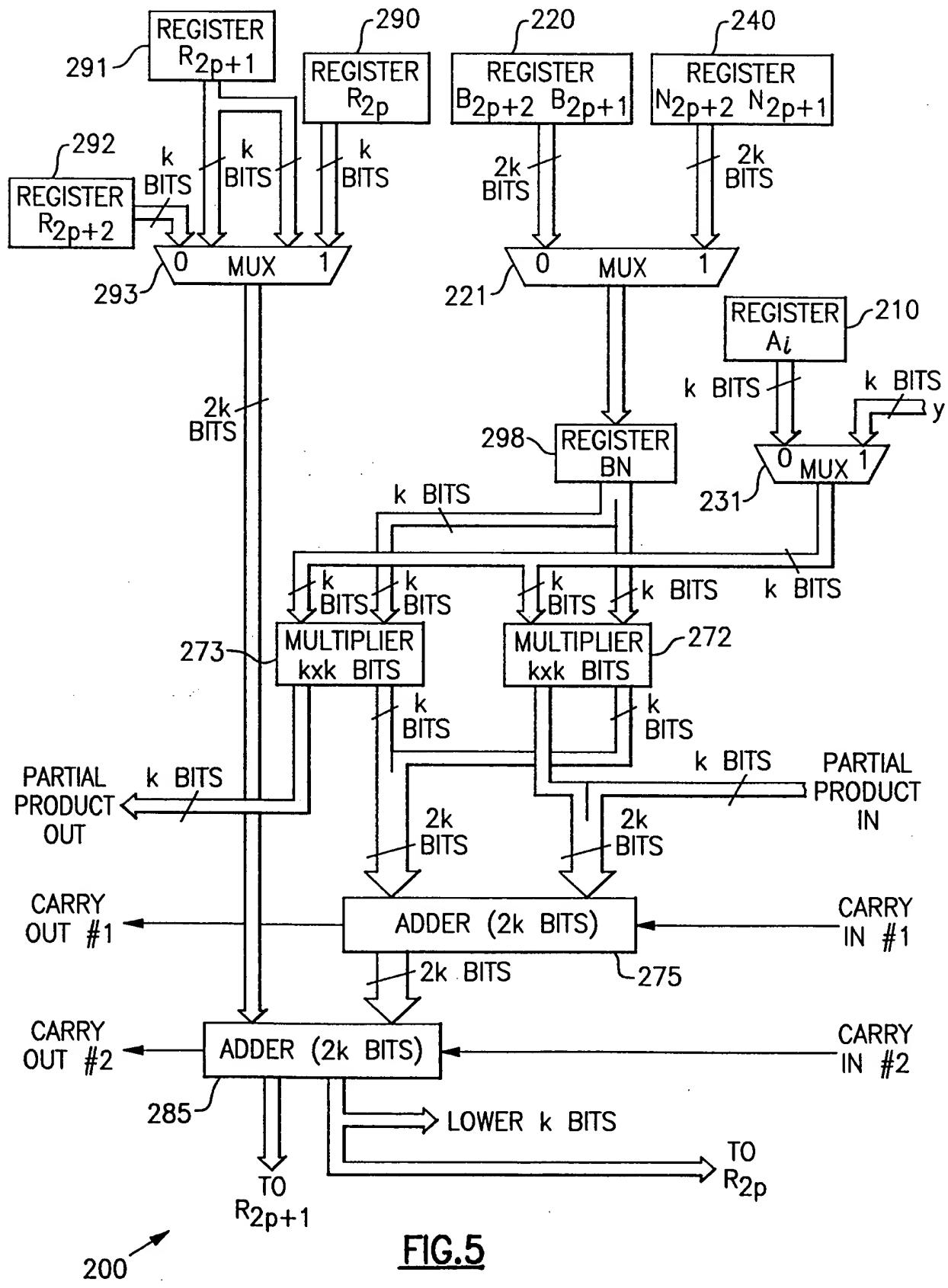


FIG.4A

FIG.5

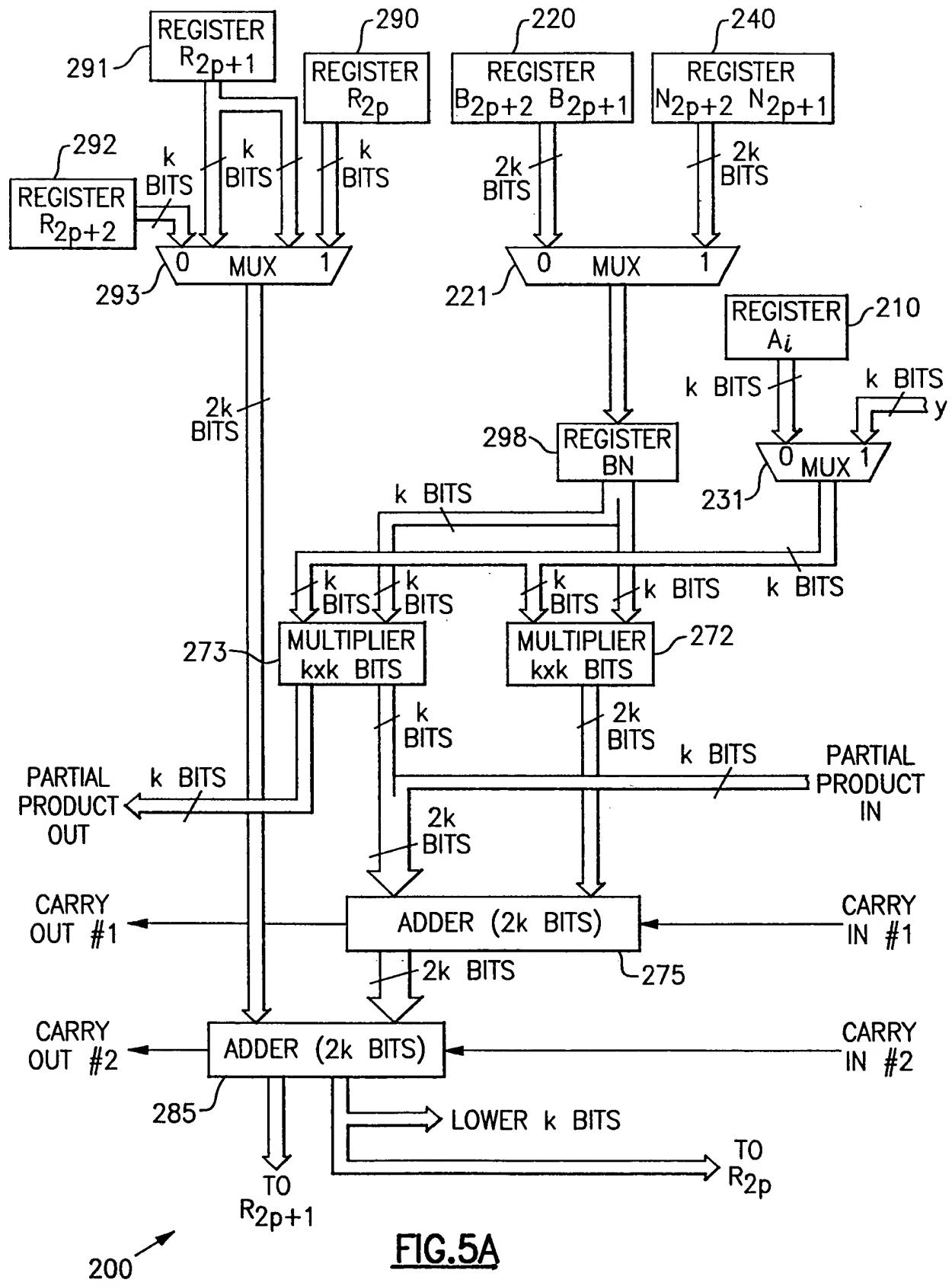


FIG.5A

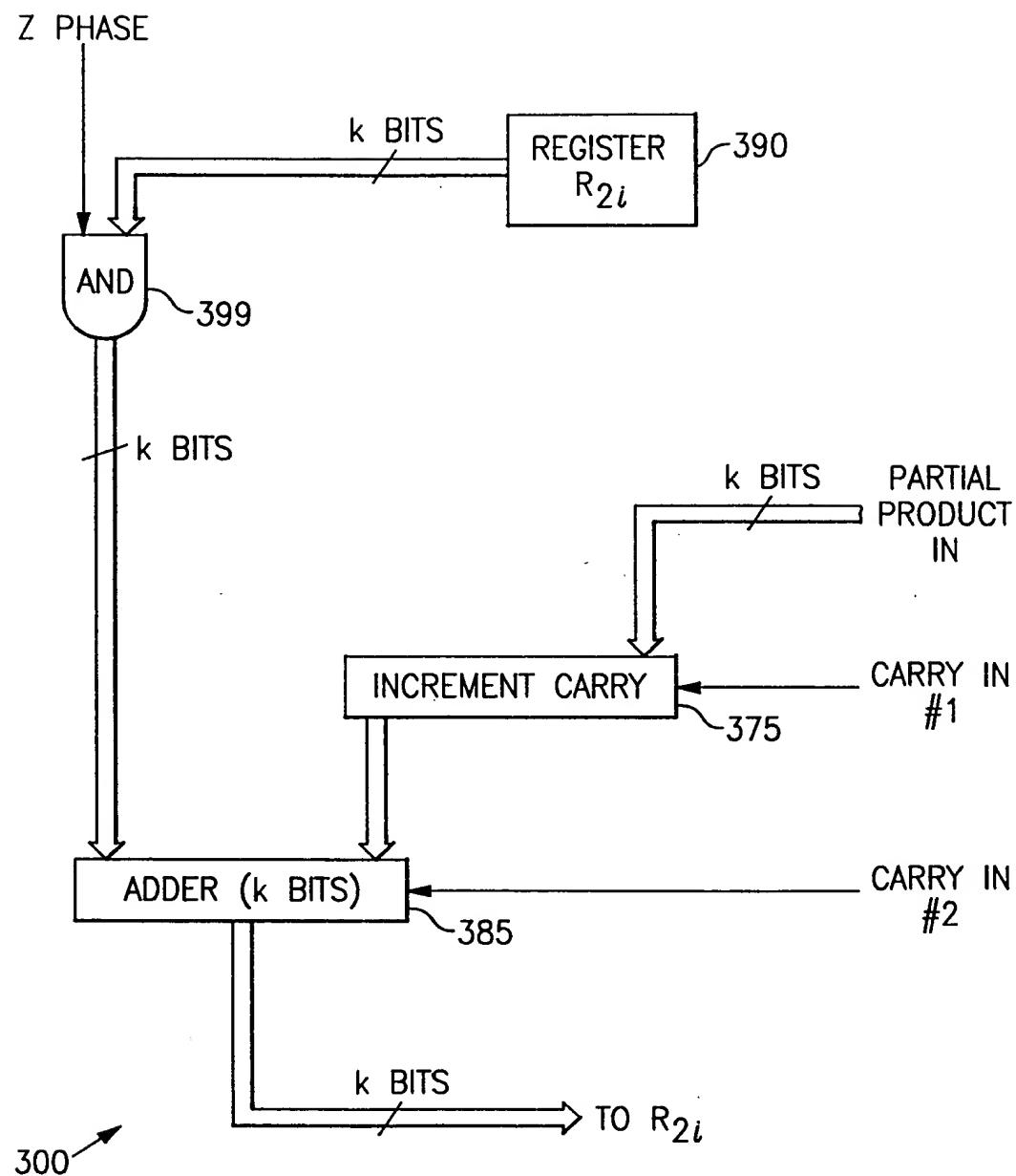


FIG.6

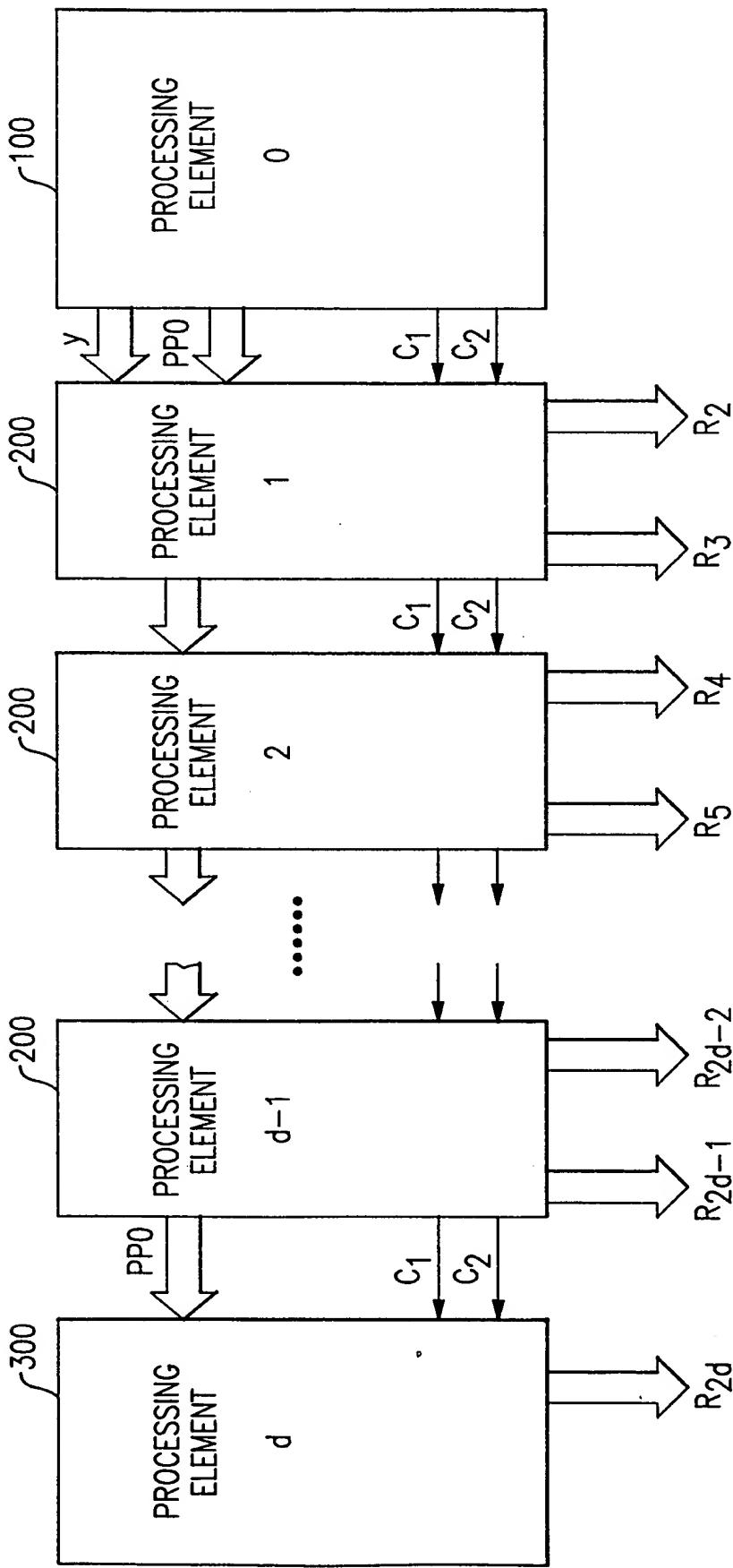


FIG.7

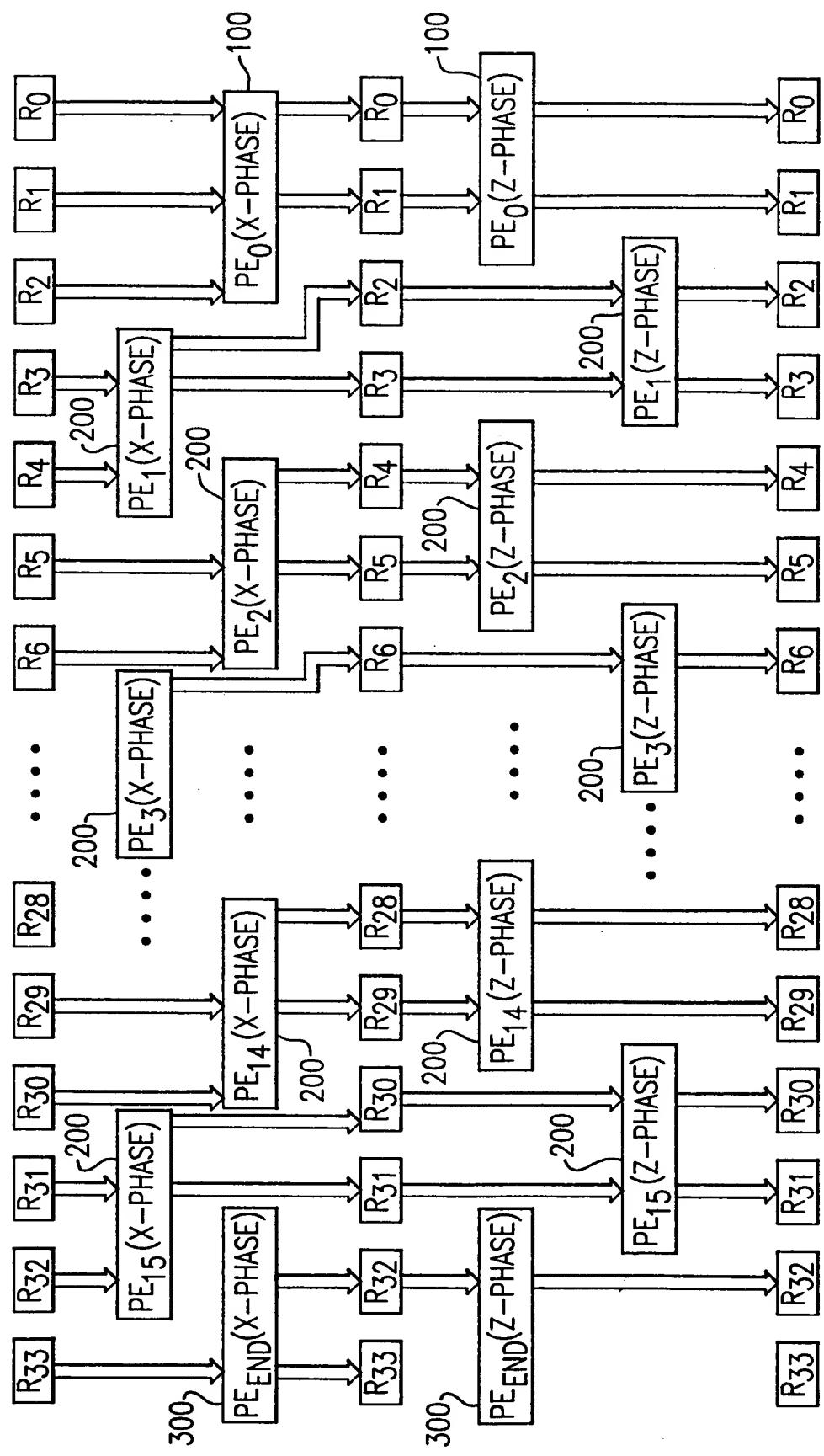


FIG. 8

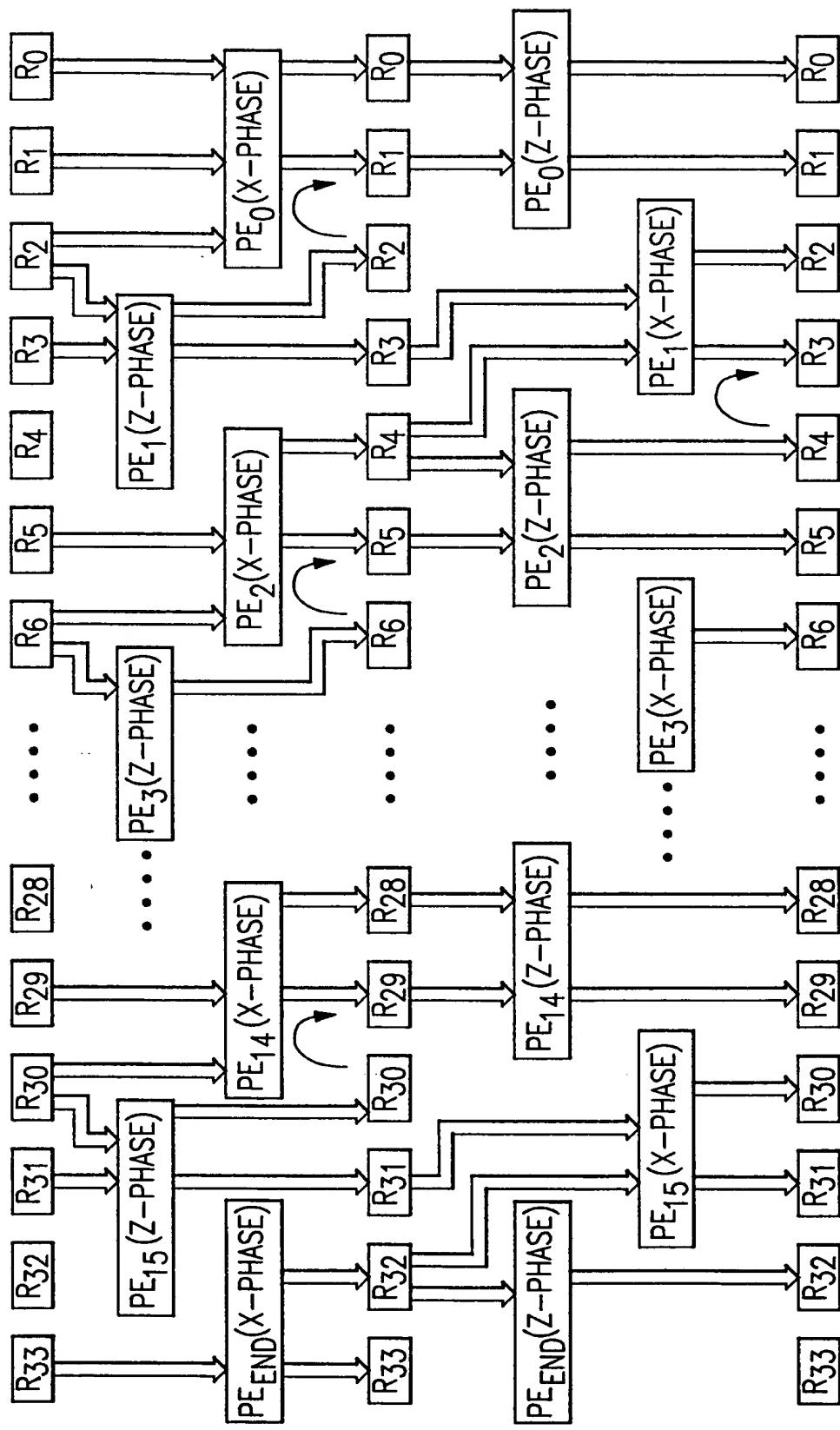


FIG.9

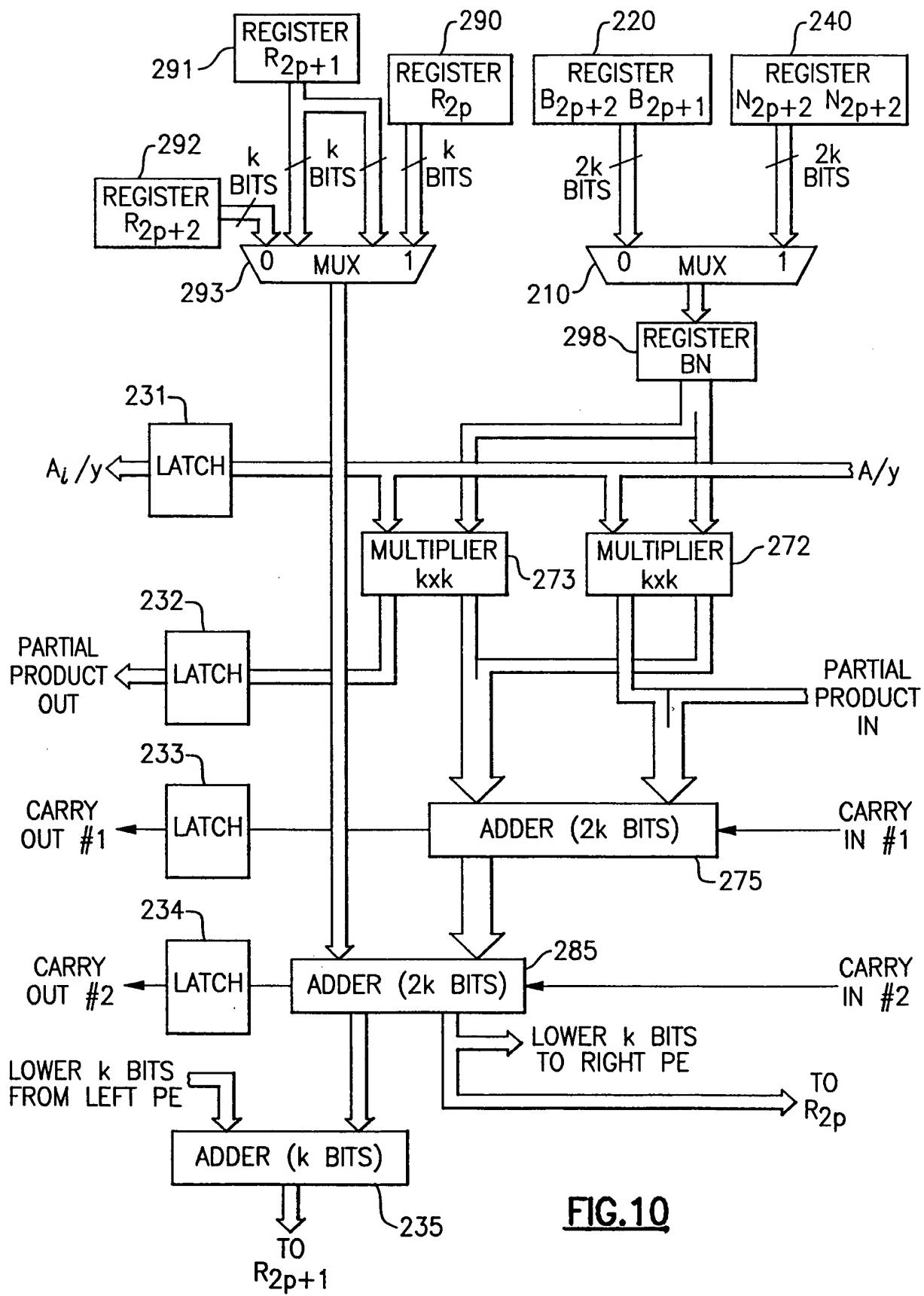
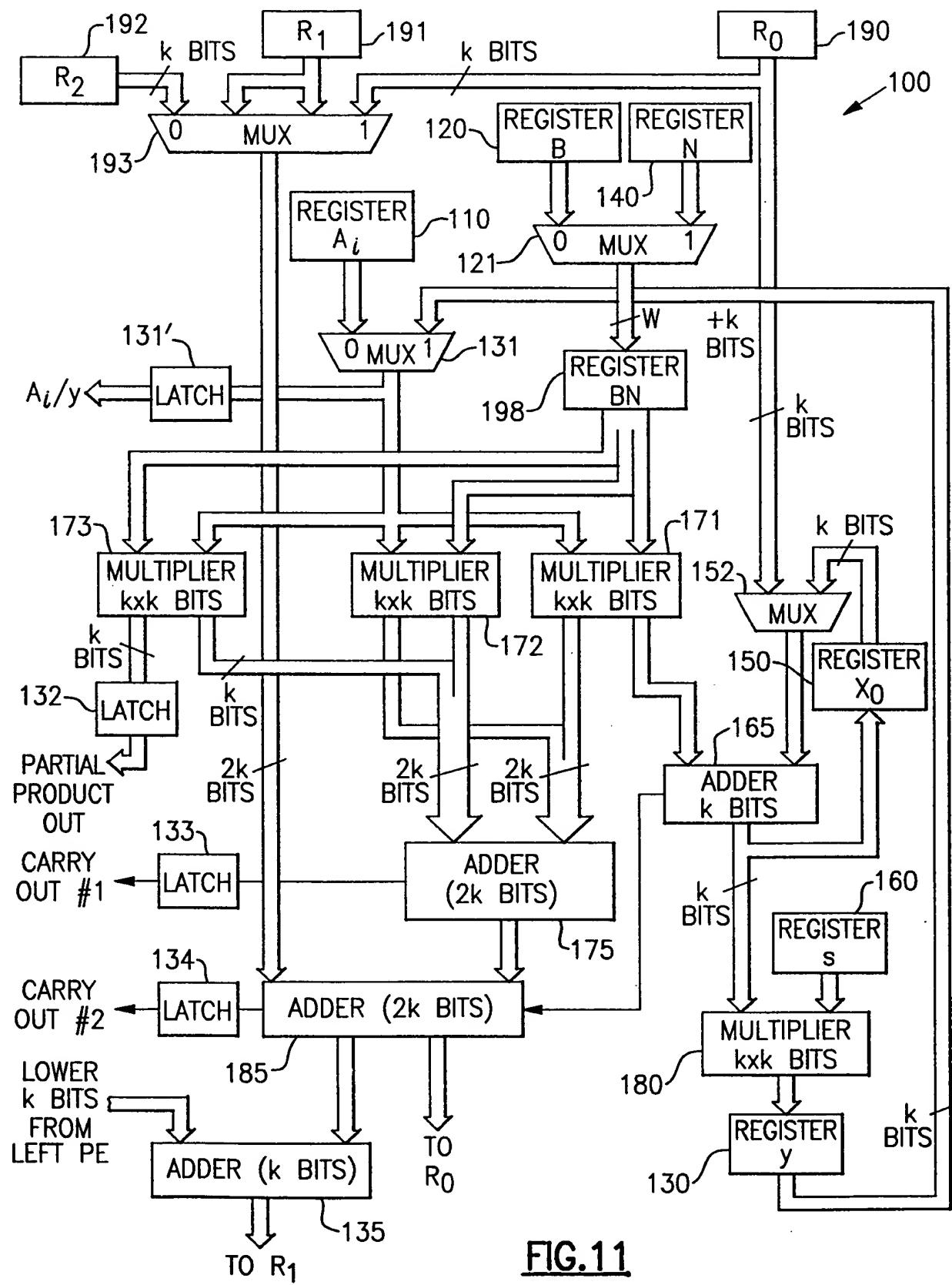


FIG.10

FIG.11

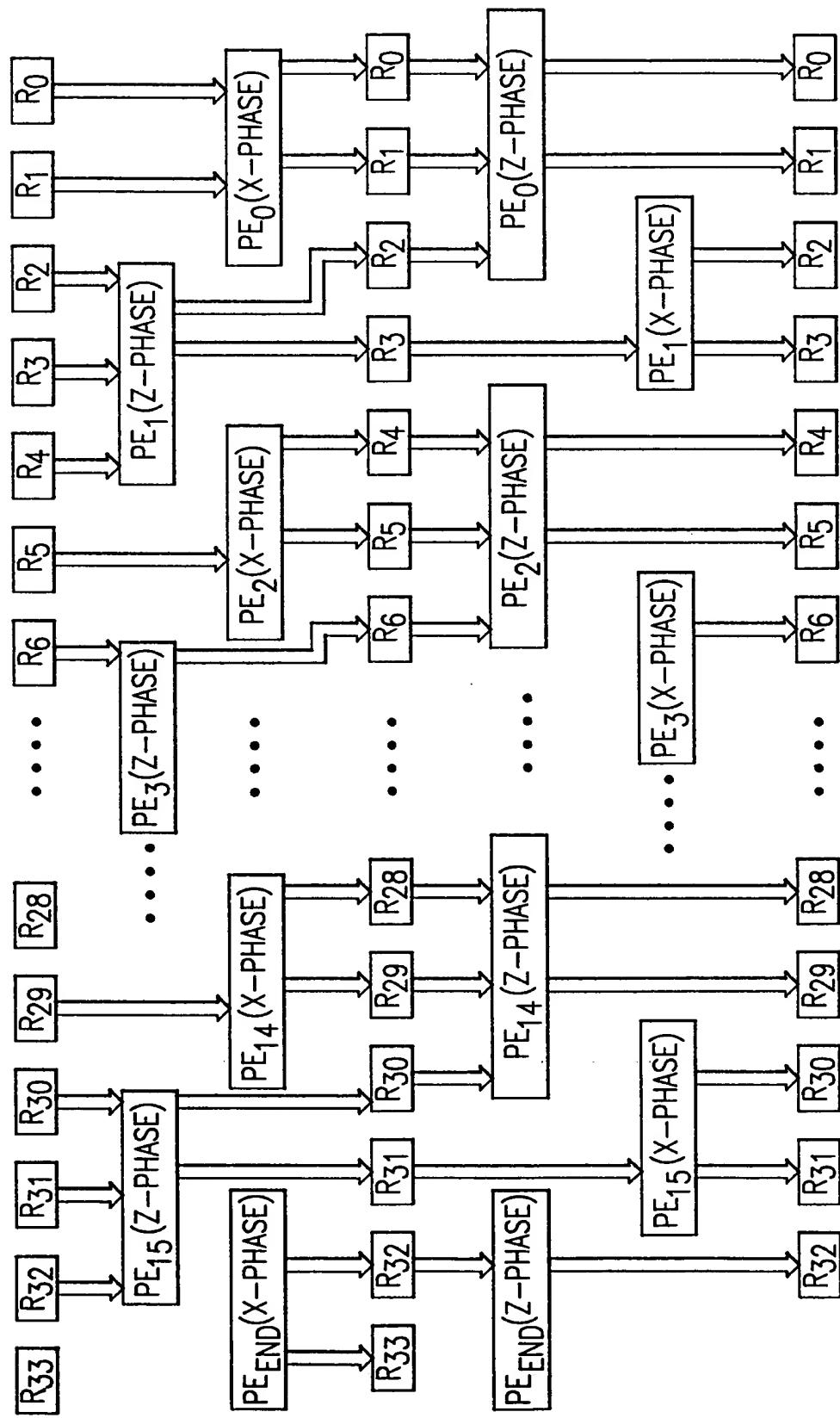


FIG.12

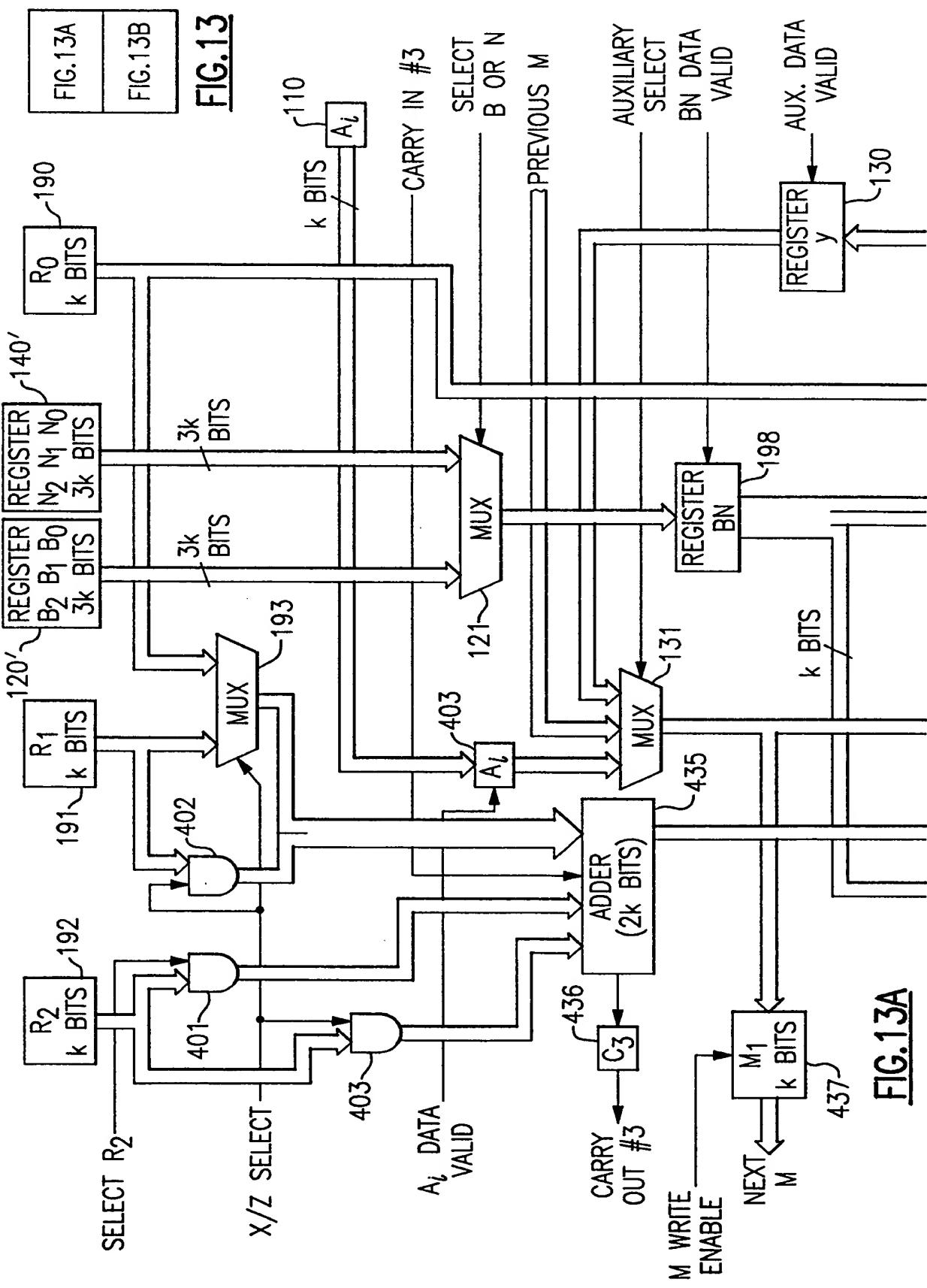
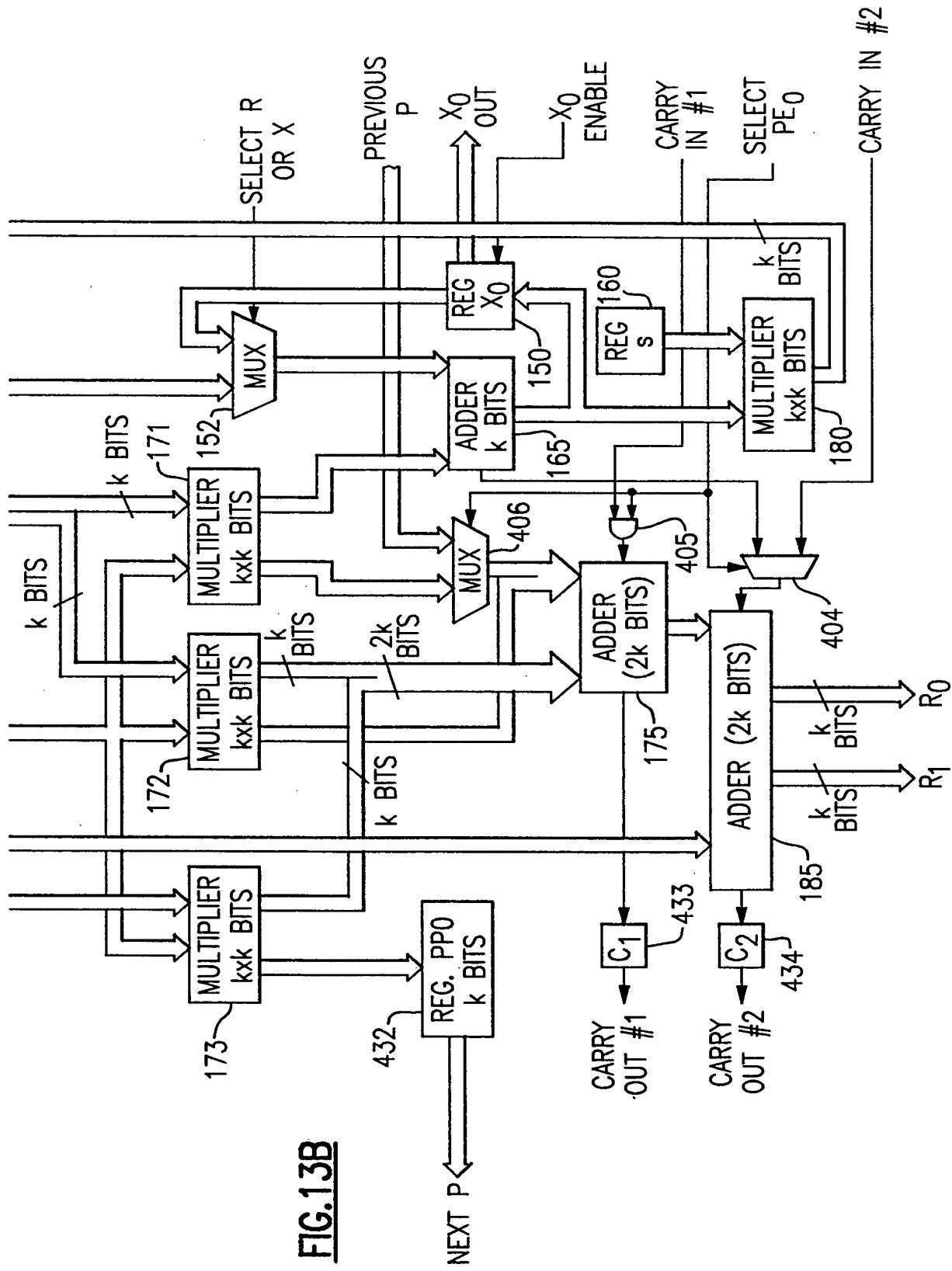


FIG.13A



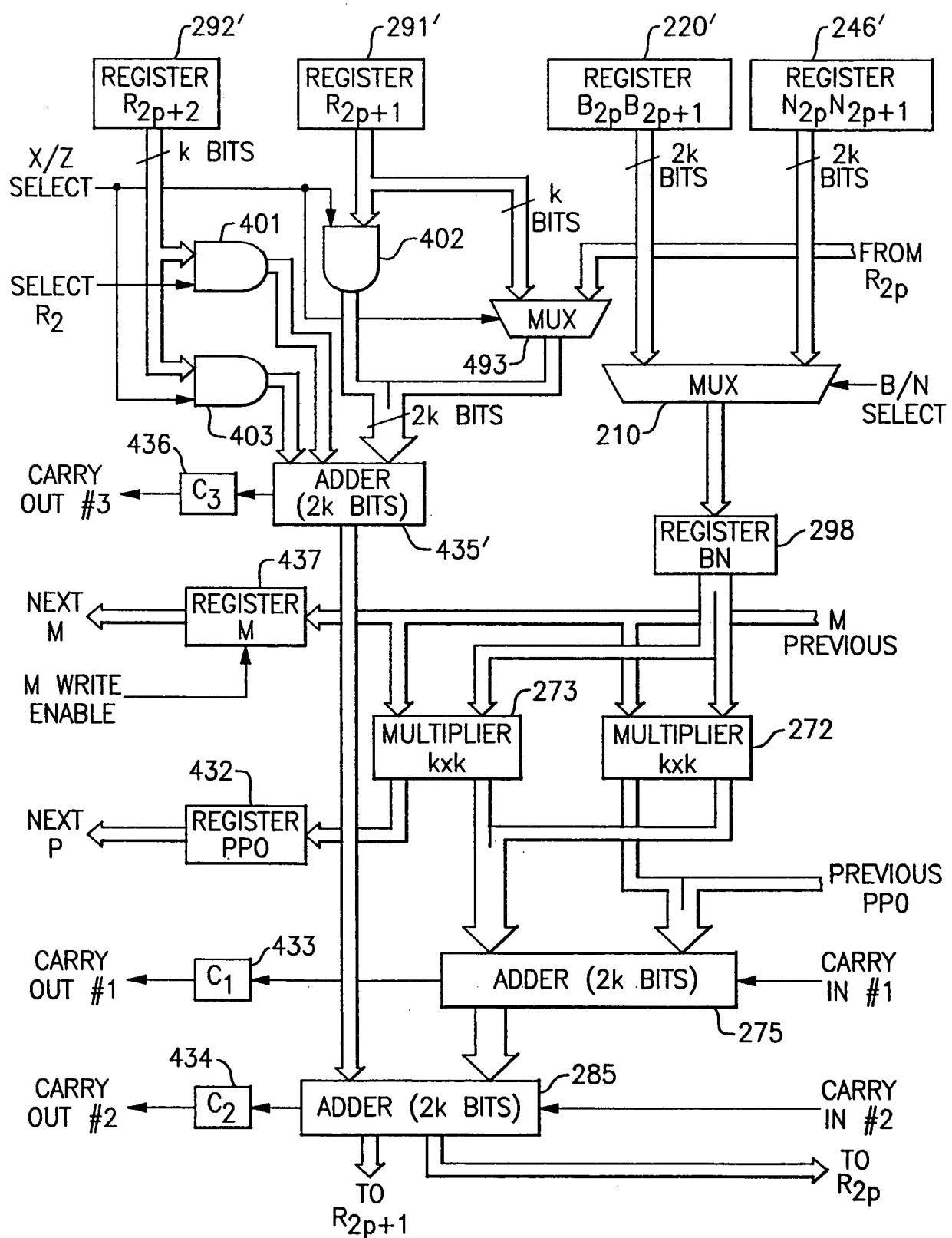


FIG.14

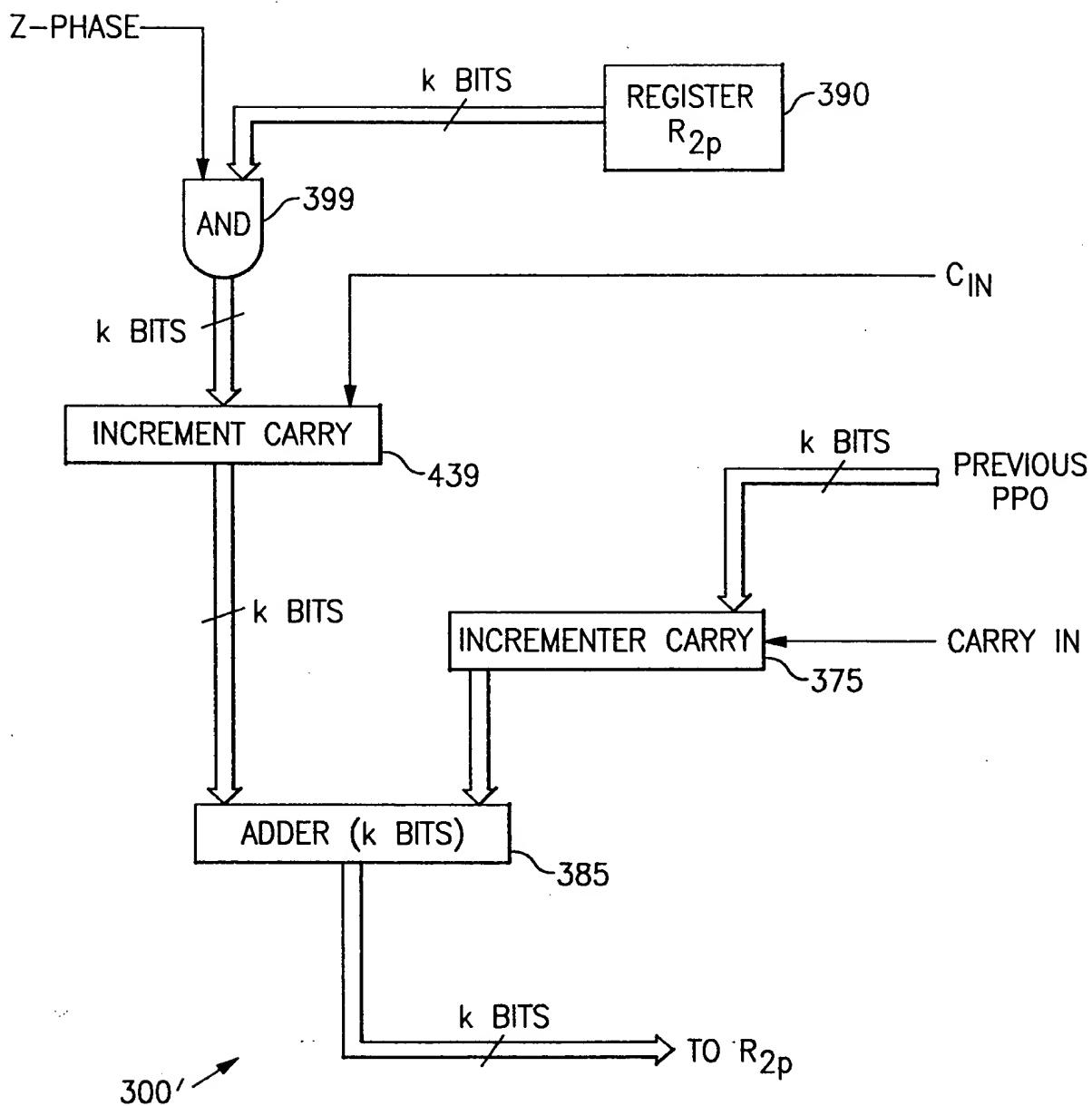


FIG.15

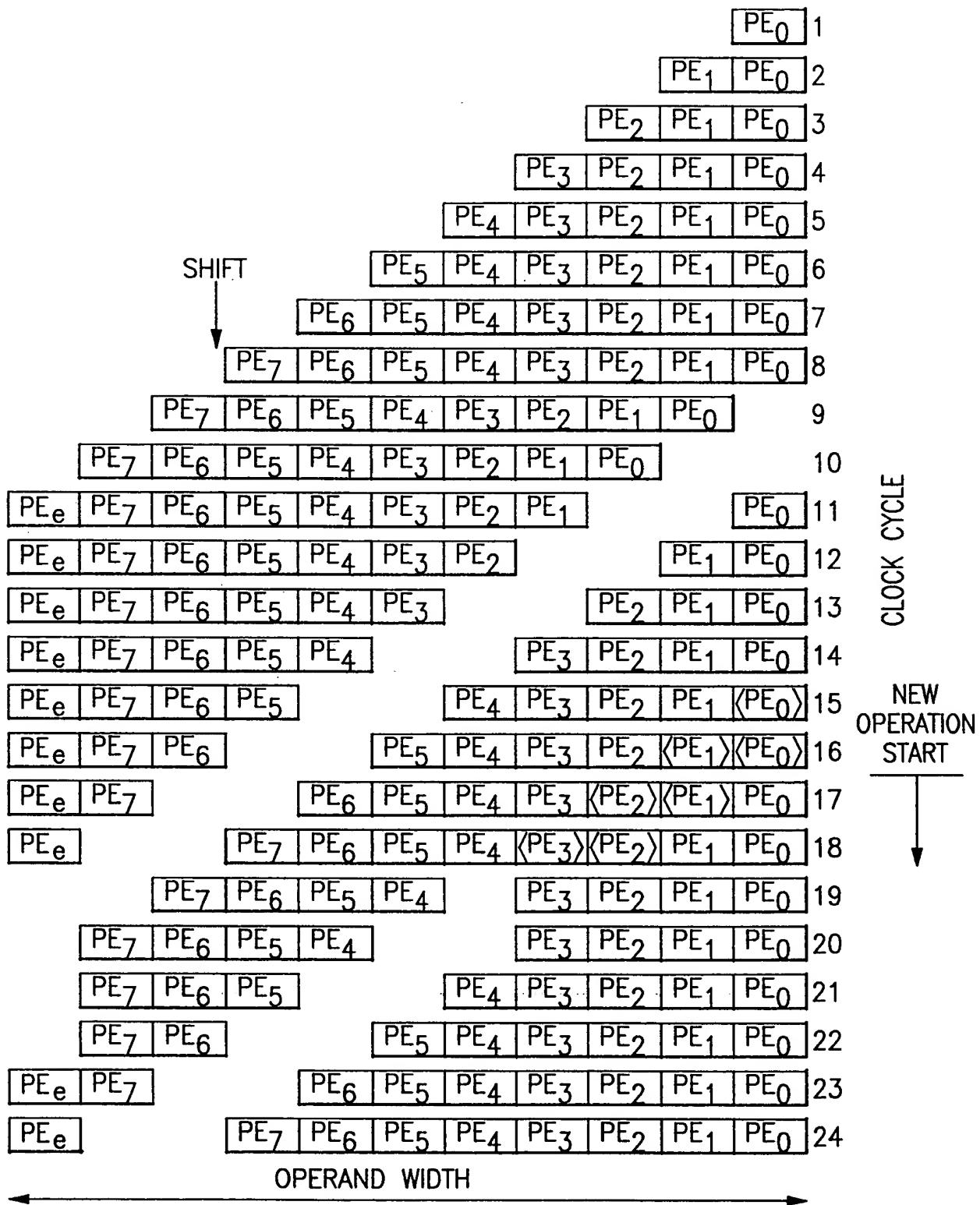


FIG.16

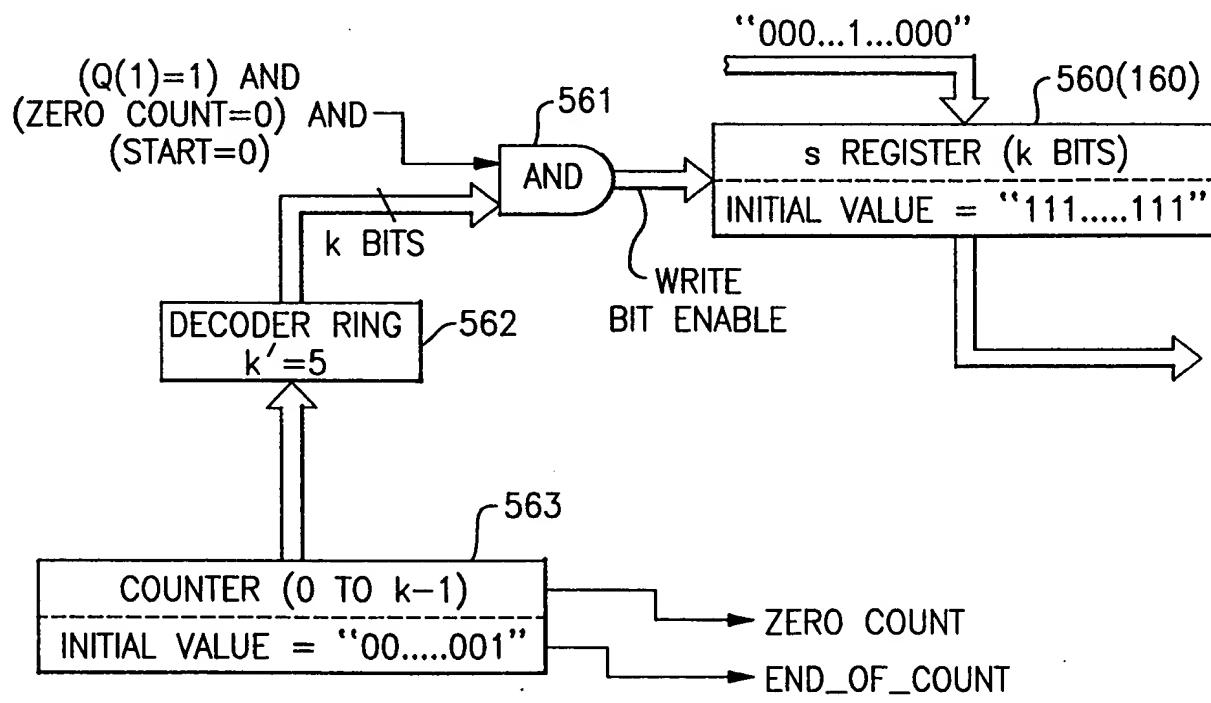
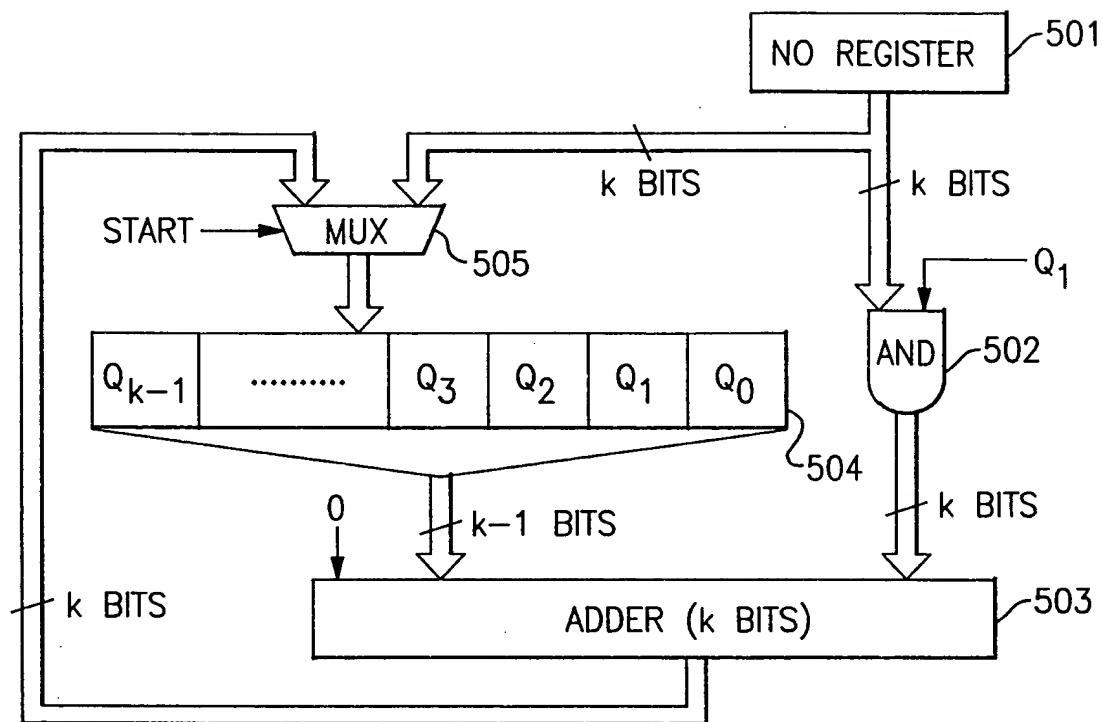


FIG.17

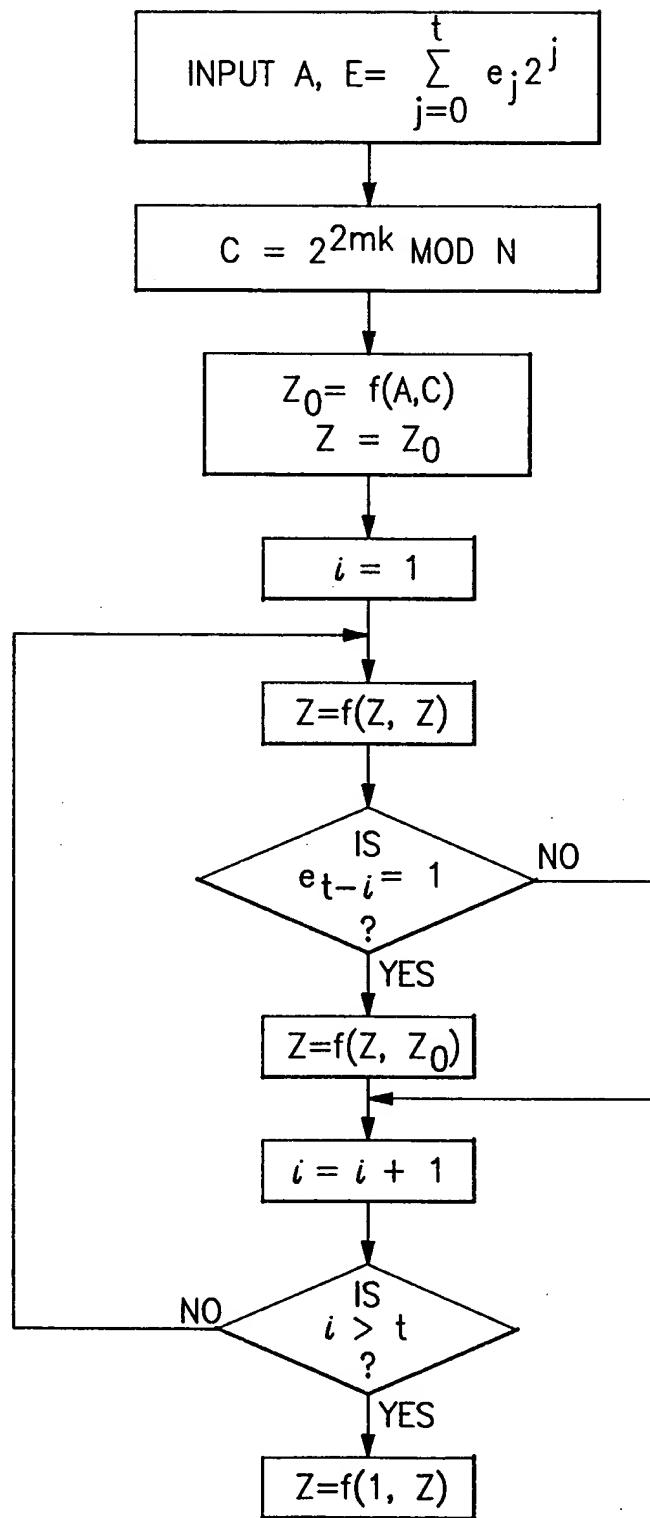


FIG.18

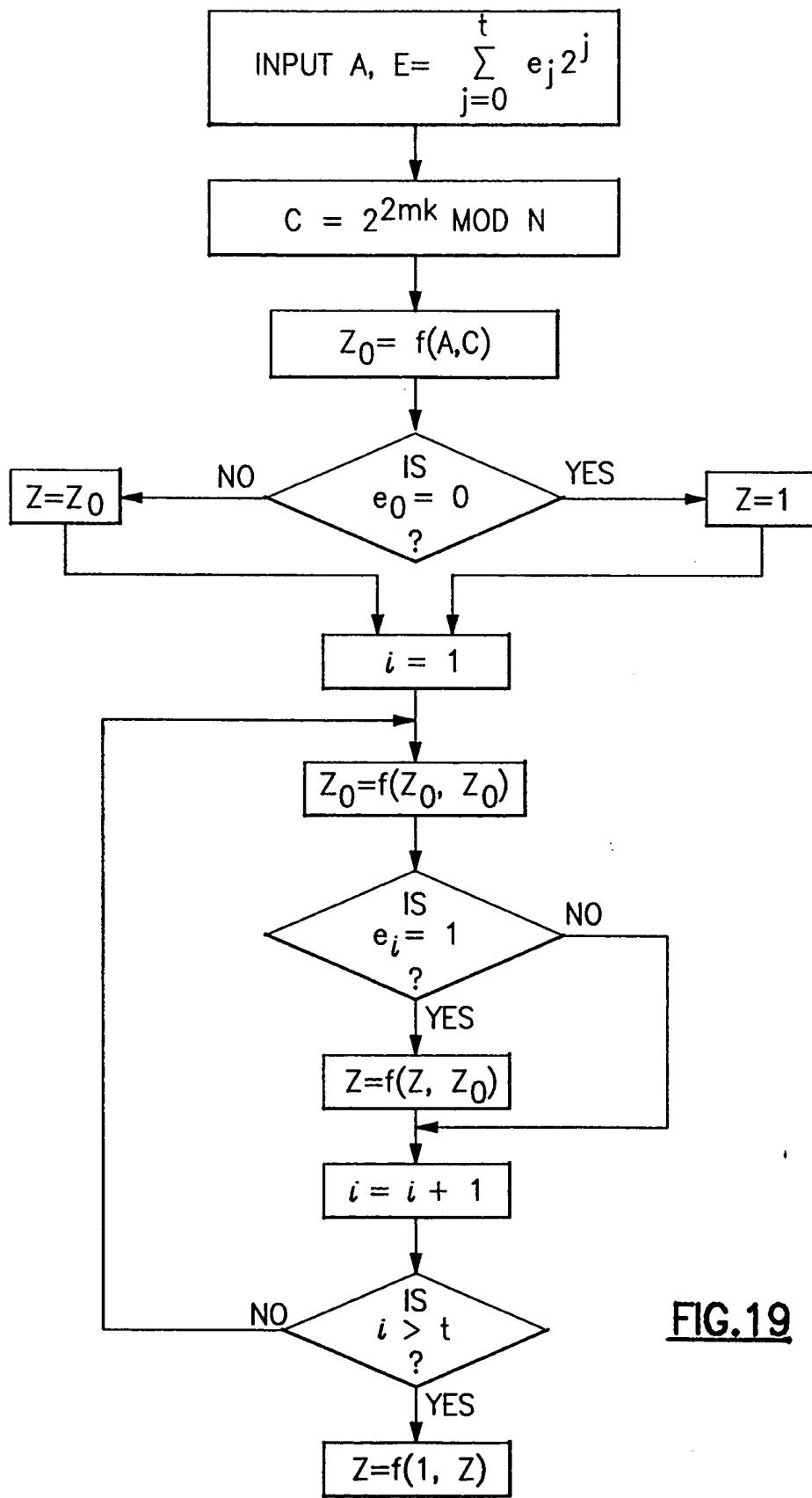


FIG.19

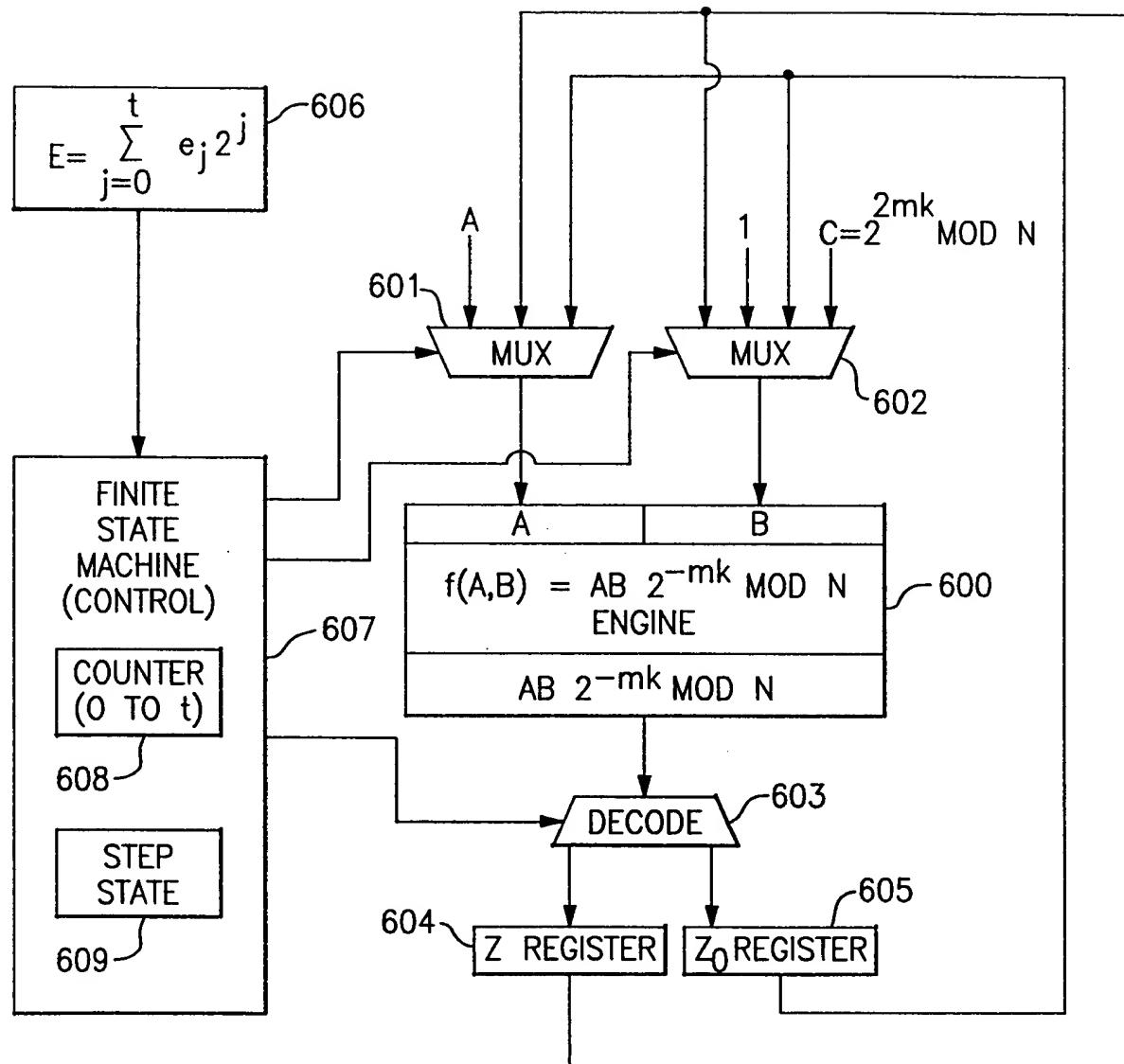
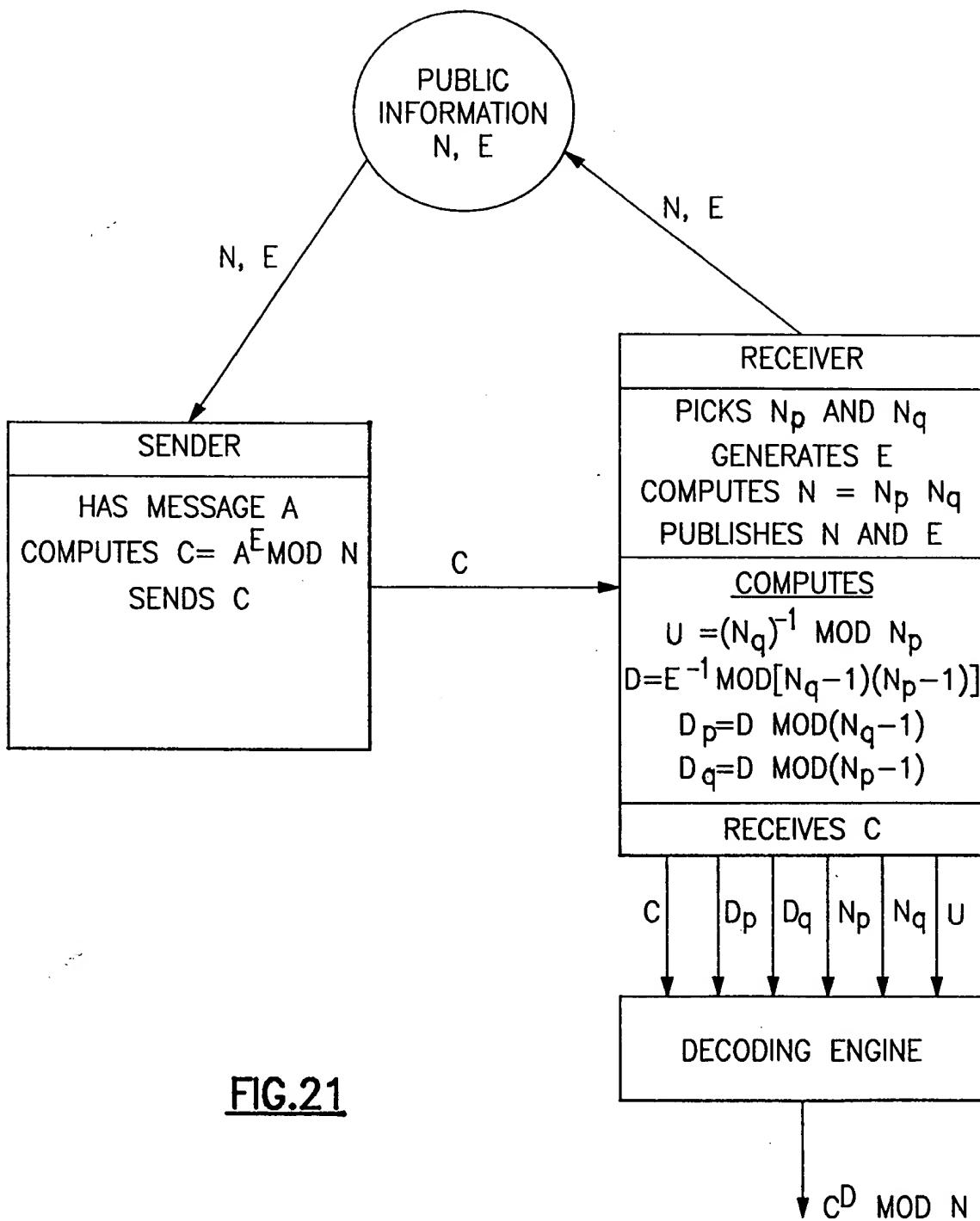


FIG.20



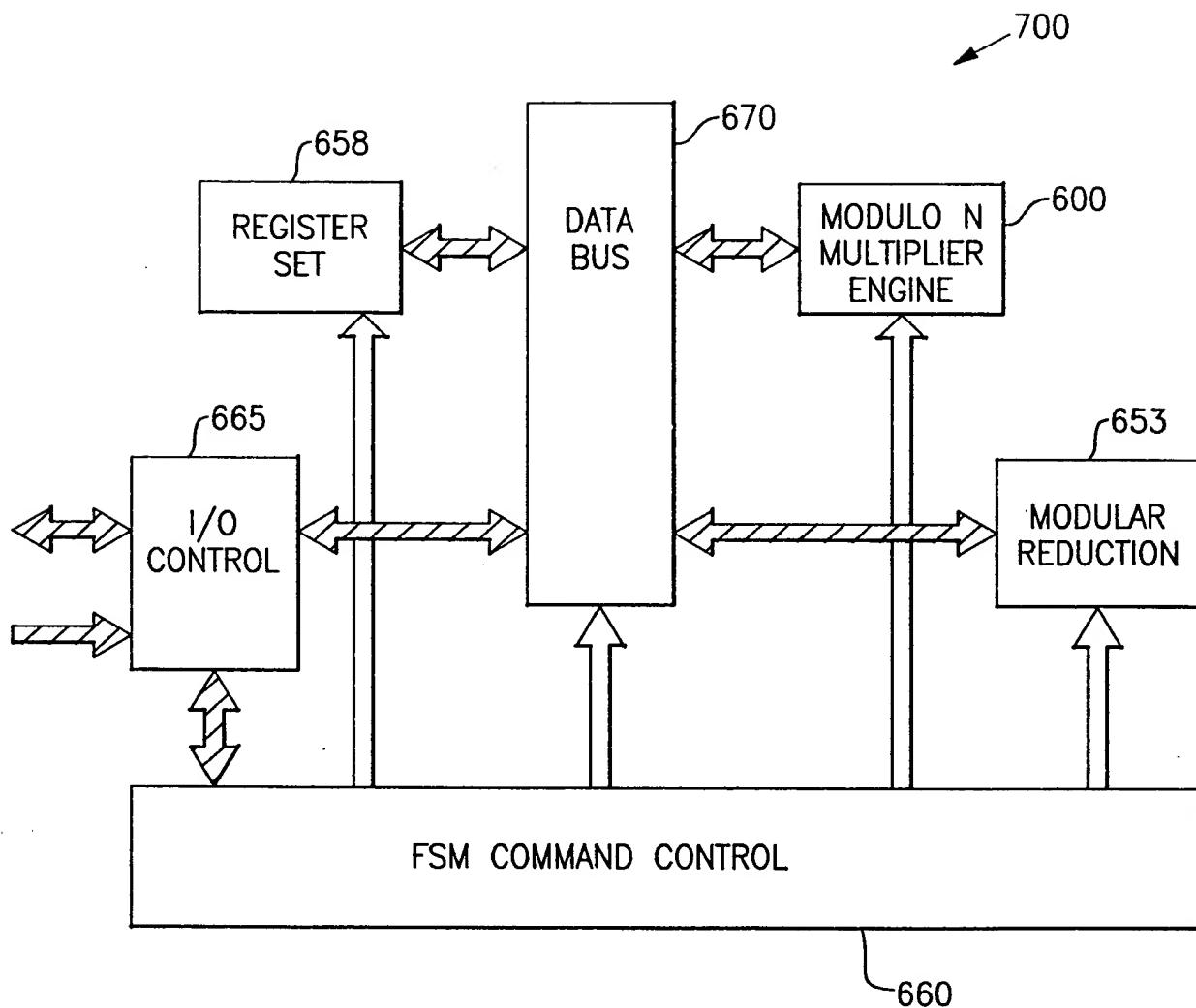


FIG.22

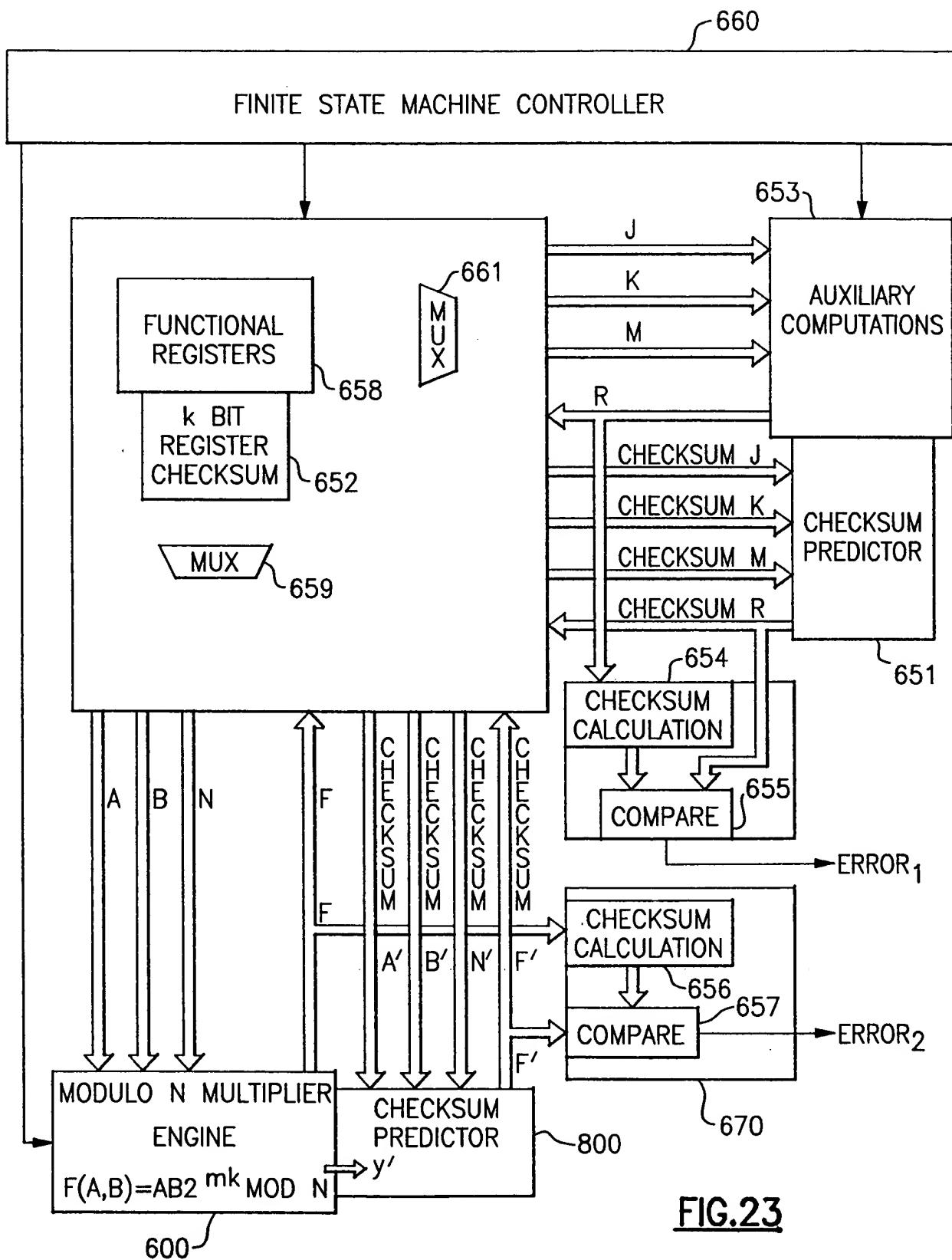


FIG.23

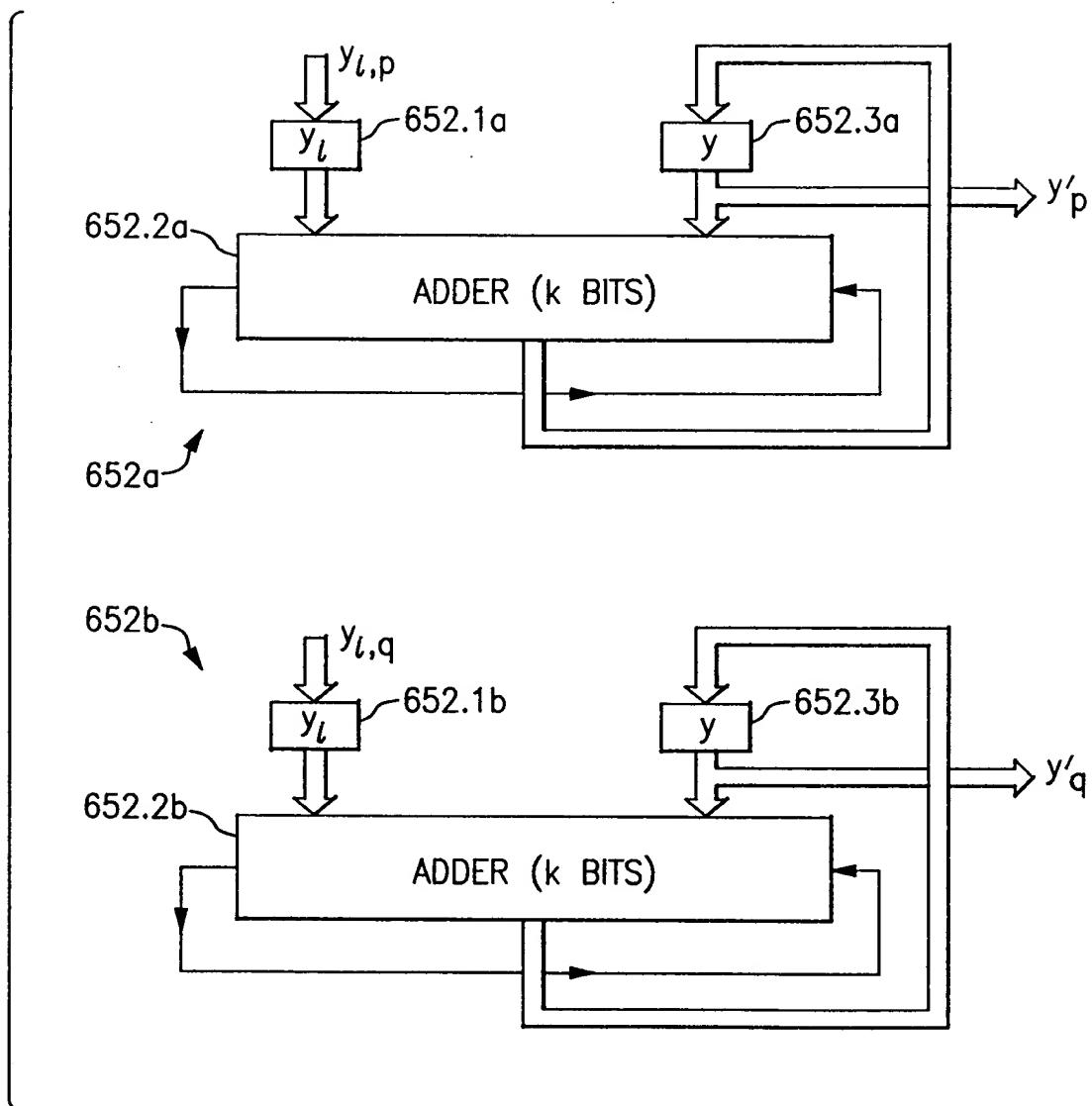


FIG.24

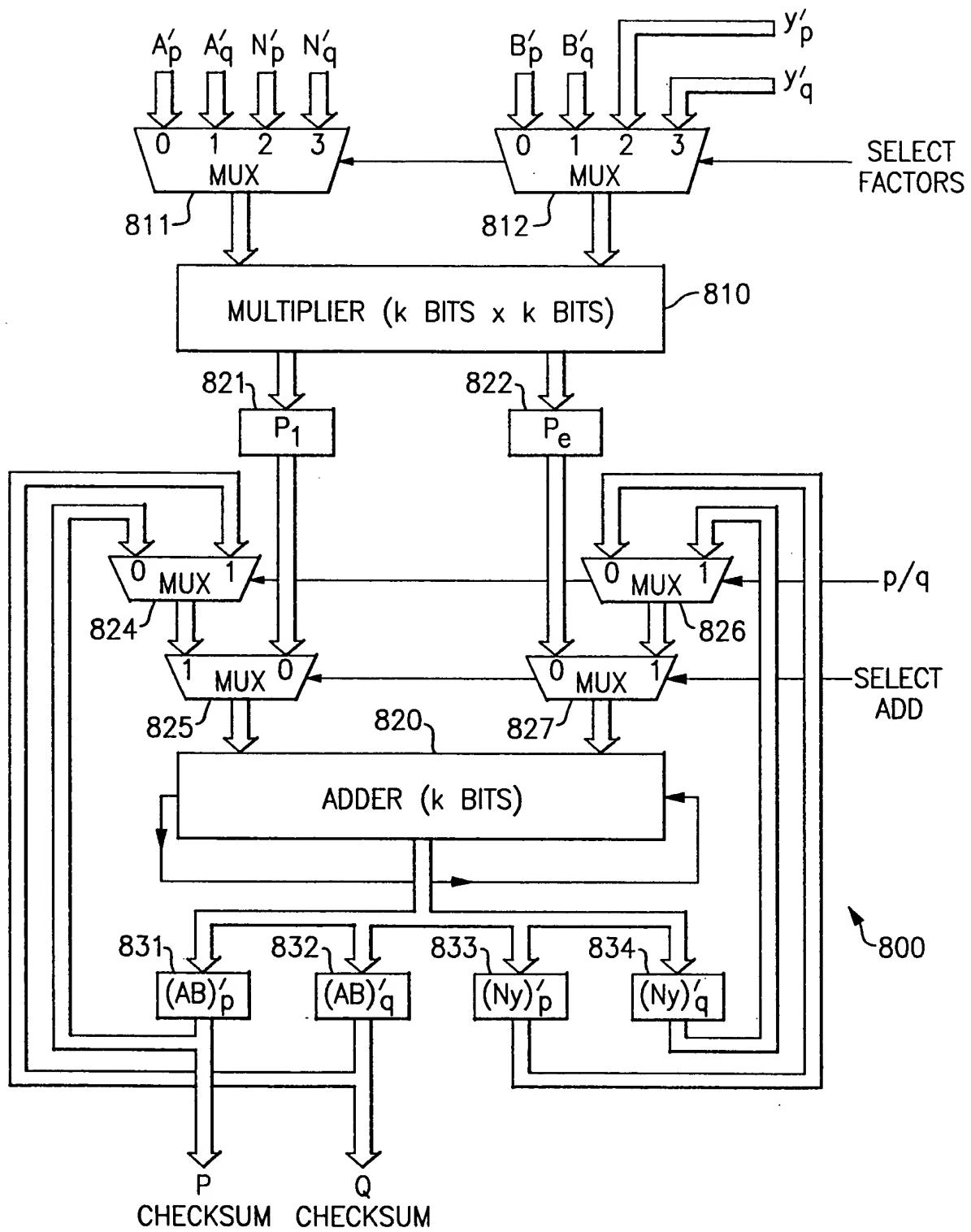


FIG.25

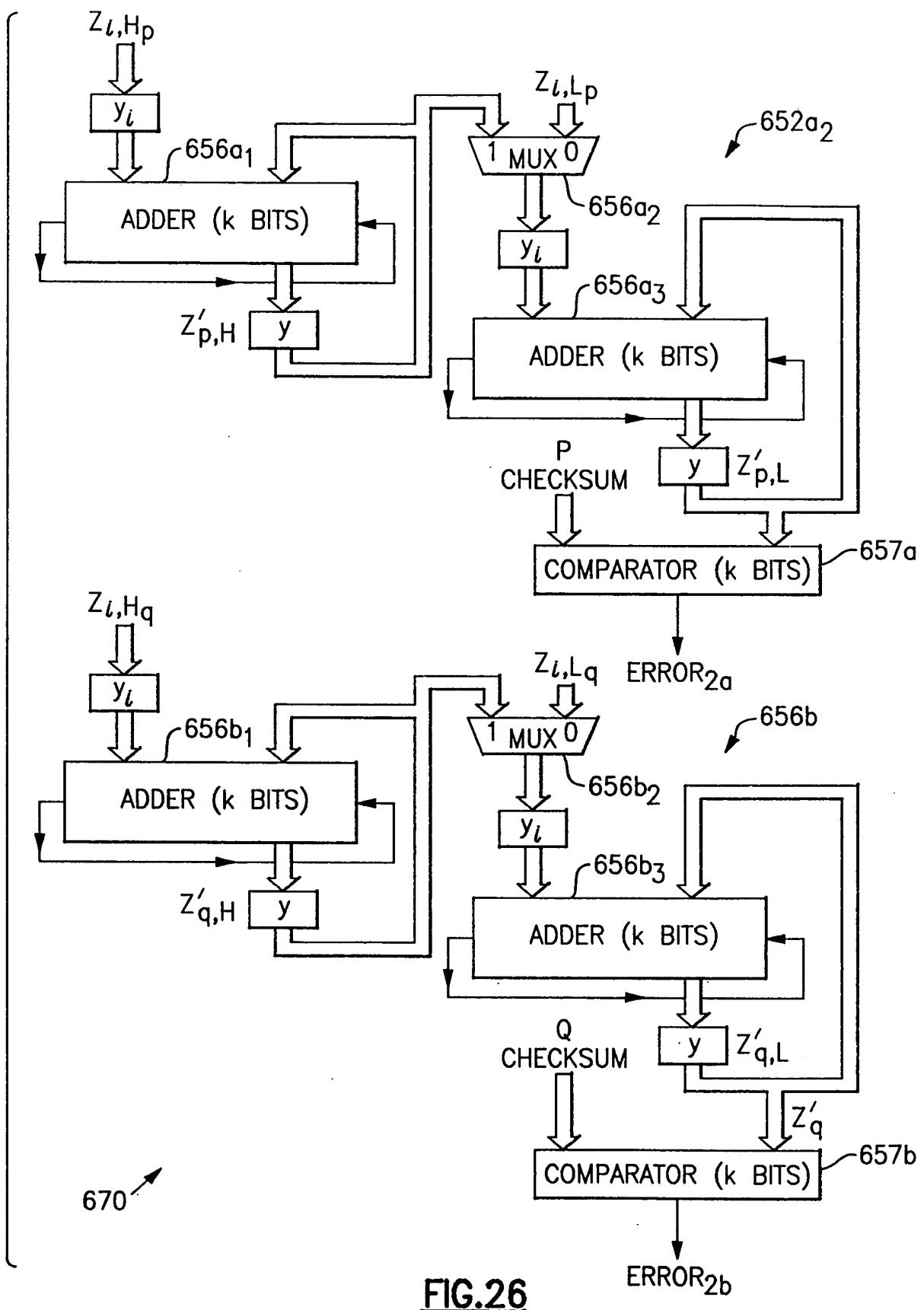


FIG.26